

ACPL-K49T

Wide Operating Temperature Automotive R²Coupler™ 20 kBd Digital Optocoupler Configurable as Low Power, Low Leakage Phototransistor



Data Sheet



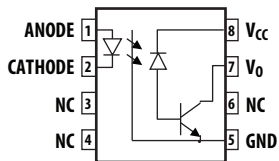
Description

The ACPL-K49T is a single channel, high temperature, high CMR, 20 kBd digital optocoupler, configurable as a low power, low leakage phototransistor, specifically for use in automotive applications. The stretched SO-8 stretched package outline is designed to be compatible with standard surface mount processes.

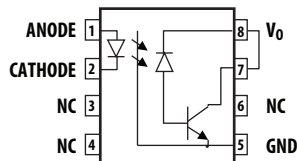
This digital optocoupler uses an insulating layer between the light emitting diode and an integrated photo detector to provide electrical insulation between input and output. Separate connections for the photodiode bias and output transistor collector increase the speed up to a hundred times over that of a conventional photo-transistor coupler by reducing the base-collector capacitance.

Avago R²Coupler isolation product provides with reinforced insulation and reliability that delivers safe signal isolation critical in automotive and high temperature industrial applications

Functional Diagram



Note: The connection of a 0.1 μ F bypass capacitor between pins 5 and 8 is recommended for 5-pin configuration.



Note: Pins 7 and 8 are externally shorted for 4-pin configuration.

Truth Table

LED	Vo
ON	LOW
OFF	HIGH

Features

- High Temperature and Reliability low speed digital interface for Automotive Application.
- 30 kV/ μ s High Common-Mode Rejection at $V_{CM} = 1500V$ (typ)
- Low Power, Low Leakage Phototransistor in a “4-pin Configuration”
- Compact, Auto-Insertable Stretched SO8 Packages
- Qualified to AEC Q100 Grade 1 Test Guidelines
- Wide Temperature Range: $-40^{\circ}C$ to $+125^{\circ}C$
- Low LED Drive Current: 4 mA (typ)
- Low Propagation Delay: 20 μ s (max)
- Worldwide Safety Approval:
 - UL 1577 approval, 5 kV_{RMS}/1 min.
 - CSA Approval
 - IEC/EN/DIN EN 60747-5-5

Applications

- Automotive Low Speed Digital Signal Isolation Interface
- Inverter Fault Feedback Signal Isolation
- Switching Power Supplies Feedback Circuit

CAUTION: It is advised that normal static precautions be taken in handling and assembly of this component to prevent damage and/or degradation which may be induced by ESD.

Ordering Information

Specify part number followed by option number (if desired).

Part number	Option (RoHS Compliant)	Package	Surface Mount	Tape & Reel	UL 5000 V _{rms} / 1 Minute rating	IEC/EN/DIN EN 60747-5-5	Quantity
ACPL-K49T	-000E	Stretched	X		X		80 per tube
	-060E	SO-8	X		X	X	80 per tube
	-500E		X	X	X		1000 per reel
	-560E		X	X	X	X	1000 per reel

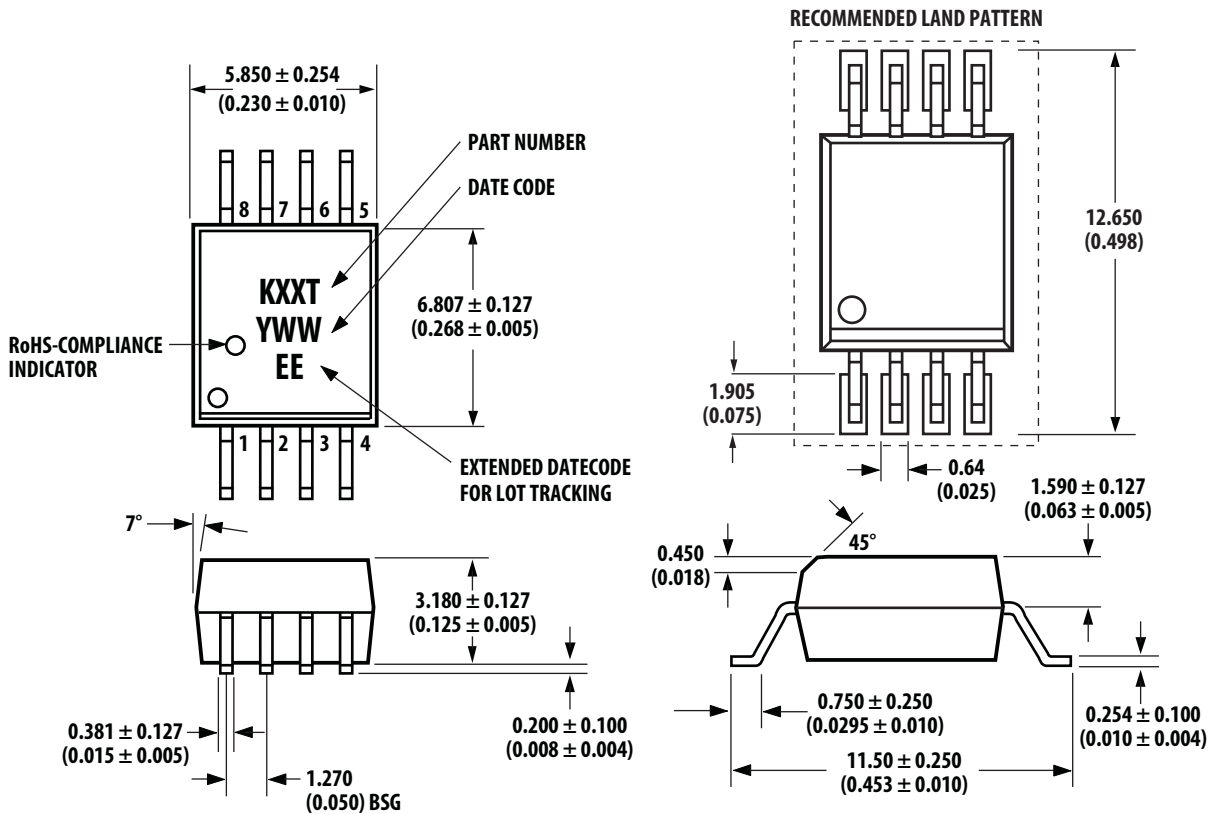
To order, choose a part number from the part number column and combine with the desired option from the option column to form an order entry.

Example 1:

ACPL-K49T-560E to order product of SSO-8 Surface Mount package in Tape and Reel packaging with IEC/EN/DIN EN 60747-5-5 Safety Approval in RoHS compliant.

Option datasheets are available. Contact your Avago sales representative or authorized distributor for information.

Outline Drawing (Stretched S08)



Dimensions in millimeters and (inches).

Note:

Lead coplanarity = 0.1 mm (0.004 inches).

Floating lead protrusion = 0.25mm (10mils) max.

Recommended Pb-Free IR Reflow Profile

Recommended reflow condition as per JEDEC Standard, J-STD-020 (latest revision).

Note: Non-halide flux should be used

Regulatory Information

The ACPL-K49T is approved by the following organizations:

UL

Approval under UL 1577, component recognition program up to $V_{ISO} = 5 \text{ kV}_{RMS}$.

CSA

Approval under CSA Component Acceptance Notice #5.

IEC/EN/DIN EN 60747-5-5

Approval under IEC/EN/DIN EN 60747-5-5

Insulation and Safety Related Specifications

Parameter	Symbol	ACPL-K49T	Units	Conditions
Minimum External Air Gap (Clearance)	L(101)	8	mm	Measured from input terminals to output terminals, shortest distance through air.
Minimum External Tracking (Creepage)	L(102)	8	mm	Measured from input terminals to output terminals, shortest distance path along body.
Minimum Internal Plastic Gap (Internal Clearance)		0.08	mm	Through insulation distance conductor to conductor, usually the straight line distance thickness between the emitter and detector.
Tracking Resistance (Comparative Tracking Index)	CTI	175	V	DIN IEC 112/VDE 0303 Part 1
Isolation Group (DIN VDE0109)		IIIa		Material Group (DIN VDE 0109)

IEC/EN/DIN EN 60747-5-5 Insulation Related Characteristic (Option 060E and 560E)

Description	Symbol	Characteristic	Units
Installation classification per DIN VDE 0110/1.89, Table 1			
for rated mains voltage $\leq 150 \text{ V}_{rms}$		I-IV	
for rated mains voltage $\leq 300 \text{ V}_{rms}$		I-IV	
for rated mains voltage $\leq 450 \text{ V}_{rms}$		I-IV	
for rated mains voltage $\leq 600 \text{ V}_{rms}$		I-IV	
for rated mains voltage $\leq 1000 \text{ V}_{rms}$		I-III	
Climatic Classification		55/100/21	
Pollution Degree (DIN VDE 0110/1.89)		2	
Maximum Working Insulation Voltage	V_{IORM}	1140	V_{PEAK}
Input to Output Test Voltage, Method b $V_{IORM} \times 1.875 = V_{PR}$, 100% Production Test with $t_m = 1 \text{ sec}$ Partial Discharge $< 5 \text{ pC}$	V_{PR}	2137	V_{PEAK}
Input to Output Test Voltage, Method a $V_{IORM} \times 1.6 = V_{PR}$, Type and sample test, $t_m = 10 \text{ sec}$, Partial Discharge $< 5 \text{ pC}$	V_{PR}	1824	V_{PEAK}
Highest Allowable Overvoltage (Transient Overvoltage, $t_{ini} = 60 \text{ sec}$)	V_{IOTM}	8000	V_{PEAK}
Safety Limiting Values (Maximum values allowed in the event of a failure)			
Case Temperature	T_S	175	$^{\circ}\text{C}$
Input Current	$I_{S,INPUT}$	230	mA
Output Power	$P_{S,OUTPUT}$	600	mW
Insulation Resistance at T_S , $V_{IO} = 500 \text{ V}$	R_S	10^9	Ω

Absolute Maximum Ratings

Parameter	Symbol	Min.	Max.	Units	Note
Storage Temperature	T _S	-55	150	°C	
Operating Temperature	T _A	-40	125	°C	
Lead Soldering Cycle	Temperature		260	°C	
	Time		10	s	
Average Forward Input Current	I _{F(avg)}		20	mA	
Peak Forward Input Current (50% duty cycle, 1ms pulse width)	I _{F(peak)}		40	mA	
Peak Transient Input Current (< = 1 μs pulse width, 300 ps)	I _{F(trans)}		100	mA	
Reversed Input Voltage	V _R		5	V	
Input Power Dissipation	P _{IN}		30	mW	
Output Power Dissipation	P _O		100	mW	
Average Output Current	I _O		8	mA	
Peak Output Current	I _{O(pk)}		16	mA	
Supply Voltage	V _{CC}	-0.5	30	V	
Output Voltage	V _O	-0.5	20	V	

Recommended Operating Conditions

Parameter	Symbol	Min.	Max.	Units	Note
Supply Voltage	V _{CC}		20.0	V	
Operating Temperature	T _A	-40	125	°C	

Electrical Specifications (DC) for 5-Pin Configuration

Over recommended operating T_A = -40° C to 125° C, unless otherwise specified.

Parameter	Sym.	Min.	Typ.	Max.	Units	Conditions	Fig.	Note
Current Transfer Ratio	CTR	32	65	100	%	T _A = 25° C V _{CC} = 4.5 V, V _O = 0.5 V, I _F = 10 mA	1,2,4	1
		24	65					
		65	110	150		T _A = 25° C V _{CC} = 4.5 V, V _O = 0.5 V, I _F = 4 mA	1,2,4	
		50	110					
Logic Low Output Voltage	V _{OL}		0.1	0.5	V	V _{CC} = 4.5 V, I _F = 10 mA, I _O = 2.4mA	3	
			0.1	0.5		V _{CC} = 4.5 V, I _F = 4 mA, I _O = 2.0mA		
Logic High Output Current	I _{OH}		2x10 ⁻⁴	0.5	μA	T _A = 25° C V _O = V _{CC} = 5.5 V I _F = 0 mA	7	
			4x10 ⁻⁴	5		V _O = V _{CC} = 20 V		
Logic Low Supply Current	I _{CCL}		35	100	μA	I _F = 4 mA, V _O = open, V _{CC} = 20 V		
Logic High Supply Current	I _{CCH}		0.02	1	μA	T _A = 25° C I _F = 0 mA, V _O = open, V _{CC} = 20 V		
				2.5	μA			
Input Forward Voltage	V _F	1.4	1.5	1.7	V	T _A = 25° C I _F = 4 mA	6	
		1.2	1.5	1.8	V			
Input Reversed Breakdown Voltage	BV _R	5			V	I _R = 10 μA		
Temperature Coefficient of Forward Voltage	ΔV/ΔT _A		-1.5		mV/°C	I _F = 10 mA		
Input Capacitance	C _{IN}		90		pF	F = 1 MHz, V _F = 0 V		

Switching Specifications (AC) for 5-Pin Configuration

Over recommended operating ($T_A = -40^\circ\text{C}$ to 125°C), $V_{CC} = 5.0\text{V}$ unless otherwise specified.

Parameter	Sym.	Min.	Typ.	Max.	Units	Conditions	Fig.	Note
Propagation Delay Time to Logic Low at Output	t_{PHL}			20	μs	Pulse: $f = 10\text{ kHz}$, Duty cycle = 50%, $I_F = 4\text{ mA}$, $V_{CC} = 5.0\text{ V}$, $R_L = 8.2\text{ k}\Omega$, $C_L = 15\text{ pF}$, $V_{THHL} = 1.5\text{ V}$	9	
Propagation Delay Time to Logic High at Output	t_{PLH}			20	μs	Pulse: $f = 10\text{ kHz}$, Duty cycle = 50%, $I_F = 4\text{ mA}$, $V_{CC} = 5.0\text{ V}$, $R_L = 8.2\text{ k}\Omega$, $C_L = 15\text{ pF}$, $V_{THLH} = 2.0\text{ V}$	9	
Common Mode Transient Immunity at Logic High Output	$ CM_H $	15	30		$\text{kV}/\mu\text{s}$	$I_F = 0\text{ mA}$ $V_{CM} = 1500\text{ V}_{p-p}$, $T_A = 25^\circ\text{C}$ $R_L = 1.9\text{ k}\Omega$	10	4
Common Mode Transient Immunity at Logic Low Output	$ CM_L $	15	30		kV/vs	$I_F = 10\text{ mA}$		
Common Mode Transient Immunity at Logic Low Output	$ CM_L $		15		$\text{kV}/\mu\text{s}$	$I_F = 4\text{ mA}$ $V_{CM} = 1500\text{ V}_{p-p}$, $T_A = 25^\circ\text{C}$ $R_L = 8.2\text{ k}\Omega$		

Electrical Specifications (DC) for 4-Pin Configuration

Over recommended operating $T_A = -40^\circ\text{C}$ to 125°C , unless otherwise specified.

Parameter	Sym.	Min.	Typ.	Max.	Units	Conditions	Fig.	Note
Current Transfer Ratio	CTR	70	130	210	%	$T_A = 25^\circ\text{C}$, $V_{CC} = V_O = 5\text{ V}$, $I_F = 4\text{ mA}$	4	1
Current Transfer Ratio	CTR (Sat)	24 35	60 110			$I_F = 10\text{ mA}$ $V_{CC} = V_O = 0.5\text{ V}$ $I_F = 4\text{ mA}$	5	
Logic Low Output Voltage	V_{OL}		0.1 0.1	0.5 0.5	V	$I_F = 10\text{ mA}$ $I_O = 2.4\text{ mA}$ $I_F = 4\text{ mA}$ $I_O = 1.4\text{ mA}$	5	
Off-State Current	$I_{(CEO)}$		4×10^{-4}	5	μA	$V_O = V_{CC} = 20\text{ V}$, $I_F = 0\text{ mA}$	8	
Input Forward Voltage	V_F	1.4 1.2	1.5 1.5	1.7 1.8	V	$T_A = 25^\circ\text{C}$ $I_F = 4\text{ mA}$	6	
Input Reversed Breakdown Voltage	BV_R	5			V	$I_R = 10\text{ }\mu\text{A}$		
Temperature Coefficient of Forward Voltage	$\Delta V/\Delta T_A$		-1.5		$\text{mV}/^\circ\text{C}$	$I_F = 10\text{ mA}$		
Input Capacitance	C_{IN}		90		pF	$F = 1\text{ MHz}$, $V_F = 0\text{ V}$		
output Capacitance	C_{CE}		35		pF	$F = 1\text{ MHz}$, $V_F = 0\text{ V}$, $V_O = V_{CC} = 0\text{ V}$		

Switching Specifications (AC) for 4-Pin Configuration

Over recommended operating ($T_A = -40^\circ\text{C}$ to 125°C), $V_{CC} = 5.0\text{V}$ unless otherwise specified.

Parameter	Sym.	Min.	Typ.	Max.	Units	Conditions	Fig.	Note
Propagation Delay Time to Logic Low at Output	t_{PHL}		2	100	μs	Pulse: $f = 1\text{ kHz}$, Duty cycle = 50%, $I_F = 4\text{ mA}$, $V_{CC} = 5.0\text{V}$, $R_L = 8.2\text{ k}\Omega$, $C_L = 15\text{ pF}$, $V_{THHL} = 1.5\text{V}$	10	
Propagation Delay Time to Logic High at Output	t_{PLH}		19	100	μs	Pulse: $f = 1\text{ kHz}$, Duty cycle = 50%, $I_F = 4\text{ mA}$, $V_{CC} = 5.0\text{V}$, $R_L = 8.2\text{ k}\Omega$, $C_L = 15\text{ pF}$, $V_{THLH} = 2.0\text{V}$	10	
Common Mode Transient Immunity at Logic Low Output	$ CM_L $	15	30		$\text{kV}/\mu\text{s}$	$I_F = 0\text{ mA}$, $V_{CM} = 1500\text{ V}_{p-p}$, $T_A = 25^\circ\text{C}$, $R_L = 8.2\text{ k}\Omega$	12	4
Common Mode Transient Immunity at Logic Low Output	$ CM_L $	15	30		$\text{kV}/\mu\text{s}$	$I_F = 4\text{ mA}$, $V_{CM} = 1500\text{ V}_{p-p}$, $T_A = 25^\circ\text{C}$, $R_L = 8.2\text{ k}\Omega$		

Package Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions	Fig.	Note
Input-Output Momentary Withstand Voltage*	V_{ISO}	5000			V_{RMS}	$RH \leq 50\%$, $t = 1\text{ min}$; $T_A = 25^\circ\text{C}$		2, 3
Input-Output Resistance	R_{I-O}		10^{14}		Ω	$V_{I-O} = 500\text{ Vdc}$		2
Input-Output Capacitance	C_{I-O}		0.6		pF	$f = 1\text{ MHz}$; $V_{I-O} = 0\text{ V}_{DC}$		2

* The Input-Output Momentary Withstand Voltage is a dielectric voltage rating that should not be interpreted as an input-output continuous voltage rating.

Notes:

1. Current Transfer Ratio in percent is defined as the ratio of output collector current, I_O , to the forward LED input current, I_F , times 100.
2. Device considered a two terminal device: pins 1, 2, 3 and 4 shorted together, and pins 5, 6, 7 and 8 shorted together.
3. In accordance with UL 1577, each optocoupler is proof tested by applying an insulation test voltage $\geq 6000\text{ V}_{RMS}$ for 1 second.
4. Common transient immunity in a Logic High level is the maximum tolerable (positive) dV_{CM}/dt on the rising edge of the common mode pulse, V_{CM} , to assure that the output will remain in a Logic High state (i.e., $V_o > 2.0\text{V}$). Common mode transient immunity in a Logic Low level is the maximum tolerable (negative) dV_{CM}/dt on the falling edge of the common mode pulse signal, V_{CM} to assure that the output will remain in a Logic Low state (i.e., $V_o < 0.8\text{V}$).

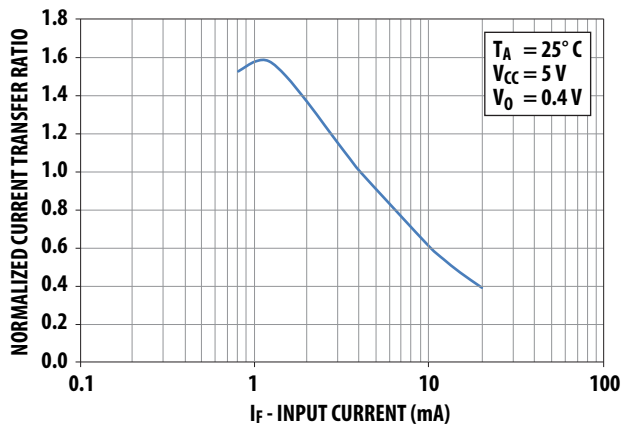


Figure 1. Current Transfer Ratio vs. Input Current

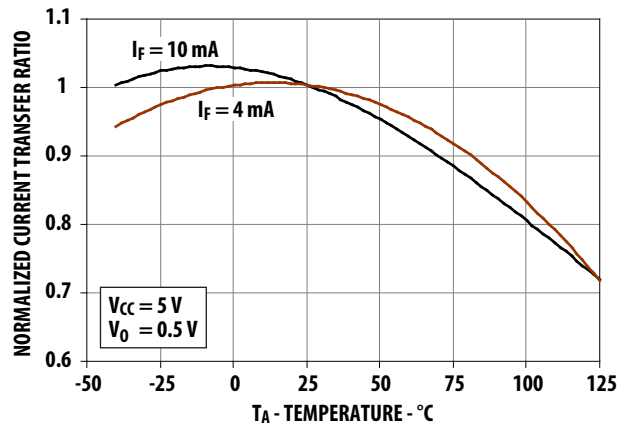


Figure 2. Normalized Current Transfer Ratio vs. Temperature

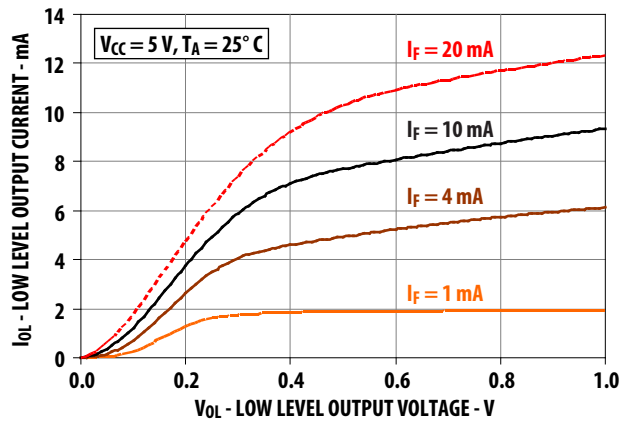


Figure 3. Typical Low Level Output Current vs Output Voltage

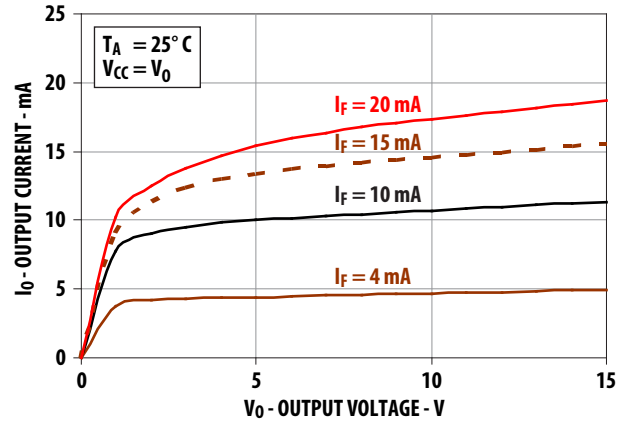


Figure 4. Output Current vs Output Voltage (4-Pin Configuration)

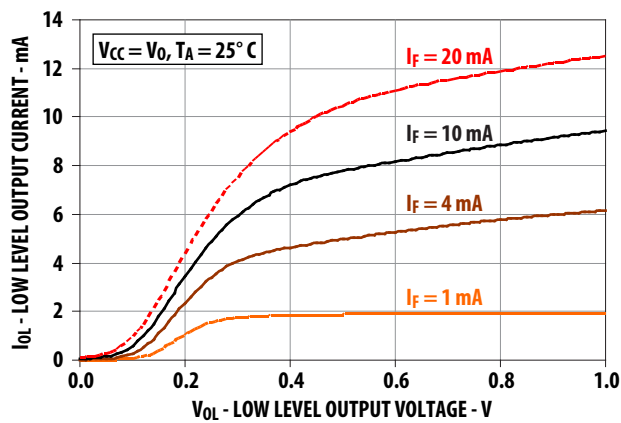


Figure 5. Typical Low Level Output Current vs Output Voltage (4-Pin Configuration)

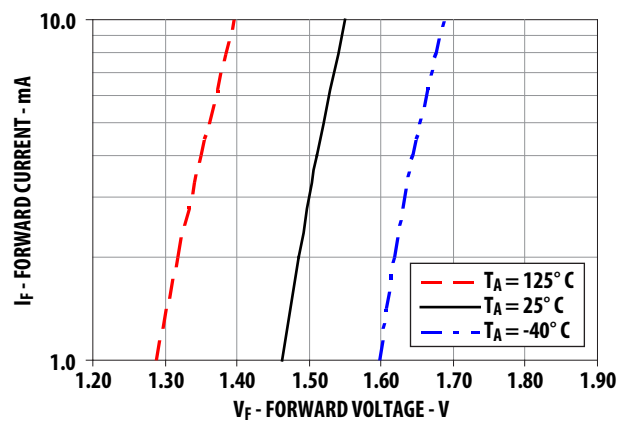


Figure 6. Typical Input Current vs Forward Voltage

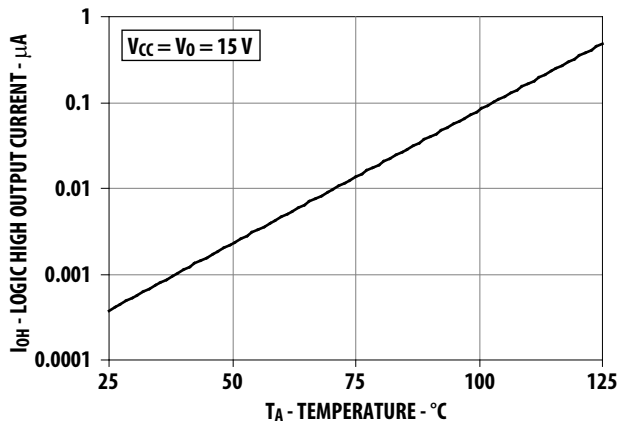


Figure 7. Typical High Level Output Current vs Temperature

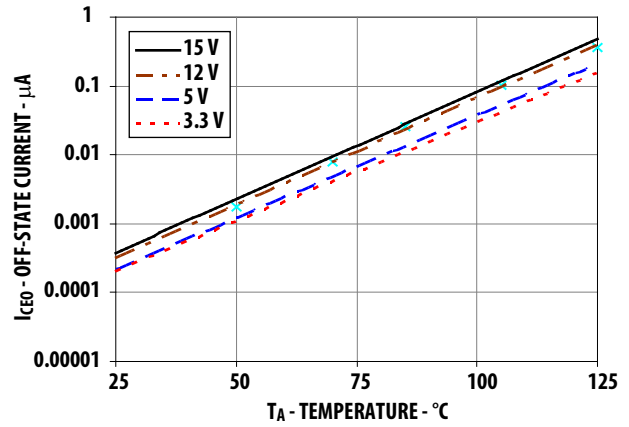


Figure 8. Typical Off-State Current vs Temperature (4-Pin Configuration)

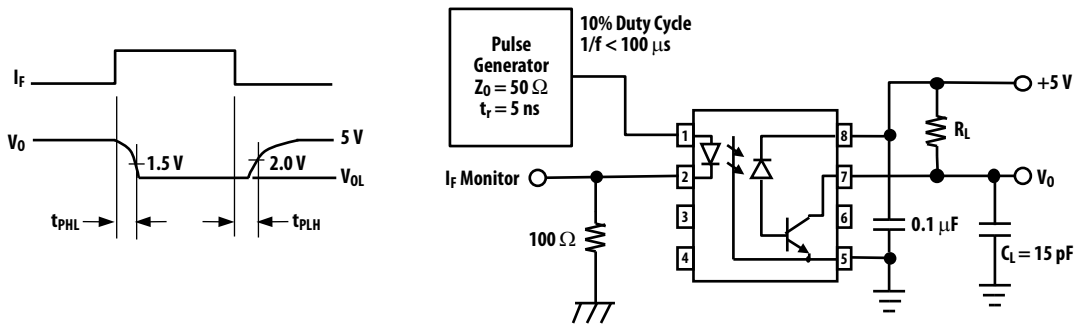


Figure 9. Switching Test Circuit (5-Pin Configuration)

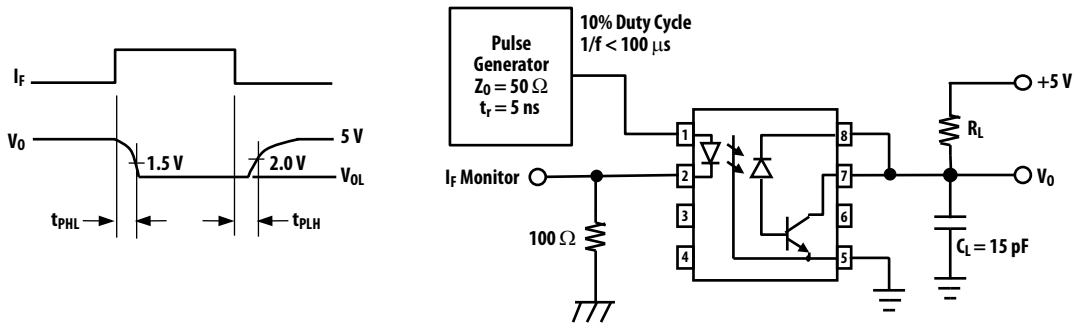


Figure 10. Switching Test Circuit (4-Pin Configuration)

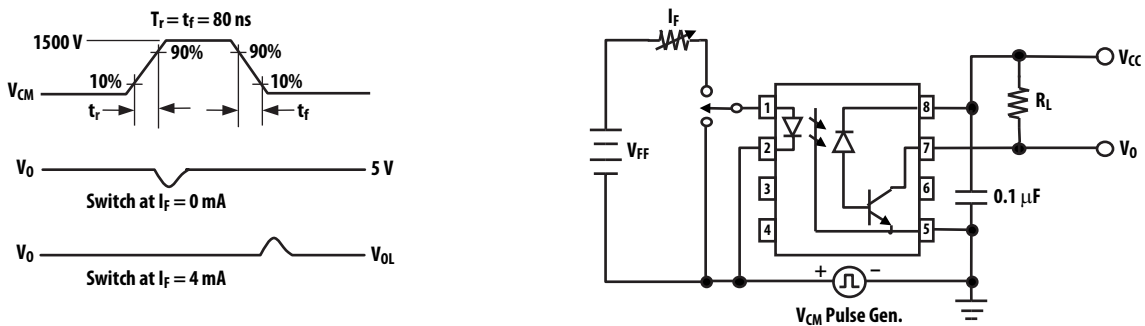


Figure 11. Test Circuit for Transient Immunity and Typical Waveforms (5-Pin Configuration)

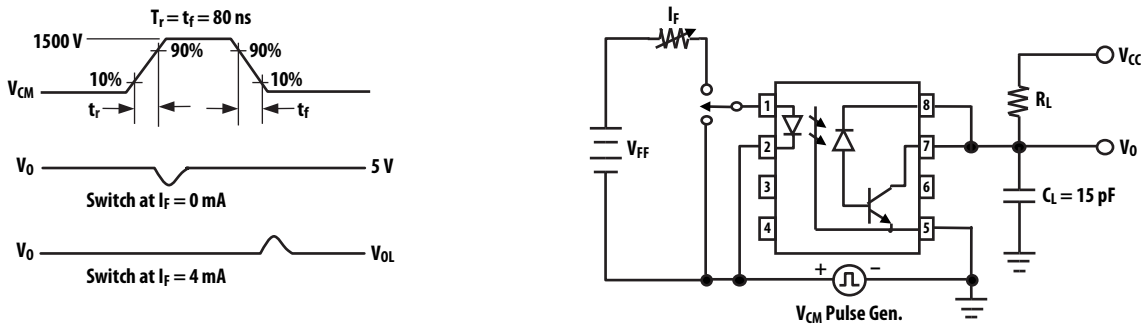


Figure 12. Test Circuit for Transient Immunity and Typical Waveforms (4-Pin Configuration)

Thermal Resistance Model for ACPL-K49T

The diagram of ACPL-K49T for measurement is shown in Figure 13. Here, one die is heated first and the temperatures of all the dice are recorded after thermal equilibrium is reached. Then, the 2nd die is heated and all the dice temperatures are recorded. With the known ambient temperature, the die junction temperature and power dissipation, the thermal resistance can be calculated. The thermal resistance calculation can be cast in matrix form. This yields a 2 by 2 matrix for our case of two heat sources.

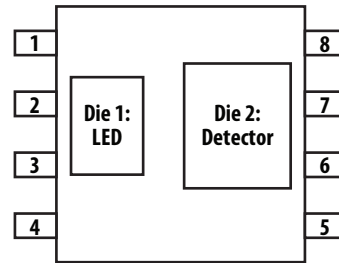


Figure 13, Diagram of ACPL-K49T for measurement

$$\begin{vmatrix} R_{11} & R_{12} \\ R_{21} & R_{22} \end{vmatrix} \times \begin{vmatrix} P_1 \\ P_2 \end{vmatrix} = \begin{vmatrix} \Delta T_1 \\ \Delta T_2 \end{vmatrix}$$

R₁₁: Thermal Resistance of Die1 due to heating of Die1

R₁₂: Thermal Resistance of Die1 due to heating of Die2.

R₂₁: Thermal Resistance of Die2 due to heating of Die1.

R₂₂: Thermal Resistance of Die2 due to heating of Die2.

P₁: Power dissipation of Die1 (W).

P₂: Power dissipation of Die2 (W).

T₁: Junction temperature of Die1 due to heat from all dice (°C).

T₂: Junction temperature of Die2 due to heat from all dice.

T_a: Ambient temperature.

ΔT₁: Temperature difference between Die1 junction and ambient (°C).

ΔT₂: Temperature difference between Die2 junction and ambient (°C).

$$T_1 = (R_{11} \times P_1 + R_{12} \times P_2) + T_a$$

$$T_2 = (R_{21} \times P_1 + R_{22} \times P_2) + T_a$$

Measurement data on a low K board:

$$R_{11} = 160^\circ\text{C/W}, R_{12} = R_{21} = 74^\circ\text{C/W}, R_{22} = 115^\circ\text{C/W}$$

For product information and a complete list of distributors, please go to our web site: www.avagotech.com